

ABSTRACT**SINGULATION SAW AND METHOD**

In a singulation saw for sawing either substrates or wafers there is provided a transport system comprising a pair of substrate carriers to locate a first substrate under a saw blade to be engaged to cut the substrate. While the first substrate is being cut, the second or other substrate carrier sequentially unloads a cut substrate, loads a new uncut substrate and then moves the uncut substrate to a vision system for determining the position of the substrate relative to the second carrier and then positions the second carrier and its substrate in a standby position ready to be cut by the saw blade cutting the first substrate.

Figure 8

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